

Peichun Hua

Computer Science and Engineering, School of Data Science
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EDUCATION

The Chinese University of Hong Kong , Shenzhen B.Eng in Computer Science Engineering Overall GPA: 3.94/4.00 — Major GPA: 4.00/4.00 — Rank: 1.5% (5/326)	September 2022 — June 2026
University of North Carolina , Chapel Hill Overall GPA: 4.00/4.00 Exchange Student	September 2024 - May 2025 Computer Science Department

PUBLICATION

- Peichun Hua**, Hanxiu Zhang, Tuo Li, and Yue Zheng. “Securing On-device Transformer with Hardware Binding and Reversible Obfuscation.” Accepted by *The 41st Annual Computer Security Applications Conference (ACSAC) 2025* (CORE: A, CCF-B, TH-CPL: B, Acceptance Rate = 84/446 ≈ 18.8%, [Code], [Paper]; Awarded “Artifact Available,” “Artifact Reviewed,” and “Artifact Reproducible” badges from IEEE).
- Peichun Hua**, Hao Li, Shanghao Shi, Zhiyuan Yu, and Ning Zhang. “Rethinking Jailbreak Detection of Large Vision Language Models with Representational Contrastive Scoring.” Submitted, ACL Rolling Review. *ARR scores: OA=3.75, Meta=4.0 (Recommended for ACL 2026 main)*. [Code], [Paper (arXiv)]
- Peichun Hua**, Hanxiu Zhang, Tuo Li, Yue Zheng, and Wenye Liu. “Live Demonstration: Hardware-Bound IP Protection for Edge-deployed Transformers.” Accepted by *IEEE International Symposium on Circuits and Systems (ISCAS) 2026* (CCF-C, TH-CPL: B)
- Xin Wang, **Peichun Hua**, Wenye Liu, and Yue Zheng. “Error-Correction-Free PUF Authentication via Scalable Open-Set Classification.” Under Review, *ACM/IEEE The 63rd Chips to Systems Conference (DAC) 2026*

AWARDS

Academic Honors

- Dean’s List, School of Data Science, CUHK-Shenzhen 2022–2023, 2023–2024
- Academic Performance Scholarship (Class B, Top <2%), School of Data Science 2023–2024
- Academic Performance Scholarship (Class C, Top <5%), School of Data Science 2022–2023
- University Research Award (with scholarship) 2024 Fall, 2025 Spring

Research Awards

- *Student Conferenceship*, 41st Annual Computer Security Applications Conference (ACSAC 2025) [ACSAC Website]
- *Artifact Available*, *Artifact Reviewed*, and *Artifact Reproducible* Badges — IEEE, for paper “Securing On-device Transformer with Hardware Binding and Reversible Obfuscation” at ACSAC 2025
- Fully Funded International Research Internship — McKelvey School of Engineering, Washington University in St. Louis Summer 2025

EXPERIENCE

School of Data Science, CUHK-Shenzhen <i>Undergraduate Research Intern</i>	Shenzhen, China September 2024 – present
McKelvey School of Engineering, Washington University in St. Louis <i>Summer Research Intern</i>	Missouri, USA May 2025 – August 2025
School of Science and Engineering, CUHK-Shenzhen <i>Undergraduate Research Intern</i>	Shenzhen, China May 2024 – May 2025

SKILLS

- **Coursework:** Achieved A grade in all listed *graduate-level* coursework
Cryptography 3D Computer Vision Hardware Security and Side-Channels
Efficient Deep Learning Research Topics in Computer Security Formal Methods in Computer Security
- **Language Proficiency:** TOEFL 108 (R29+L29+S23+W27), GRE 328(V161+Q167+3.5)